

CMOS Quad Exclusive-OR Gate

High-Voltage Types (20-Volt Rating)

■ CD4030B types consist of four independent Exclusive-OR gates. The CD4030B provides the system designer with a means for direct implementation of the Exclusive-OR function.

The CD4030B types are supplied in 14-lead hermetic dual-in-line ceramic packages (F3A suffix), 14-lead dual-in-line plastic packages (E suffix), 14-lead small-outline packages (M, MT, M96, and NSR suffixes), and 14-lead thin shrink small-outline packages (PW and PWR suffixes).

MAXIMUM RATINGS, Absolute-Maximum Values: DC SUPPLY-VOLTAGE RANGE (Voc)

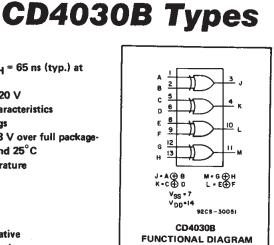
Features:

- Medium-speed operation-tpHL, tpLH = 65 ns (typ.) at VDD = 10 V, CL = 50 pF
- = 100% tested for quiescent current at 20 V
- Standardized, symmetrical output characteristics
- 5-V, 10-V, and 15-V parametric ratings
- Maximum input current of 1 µA at 18 V over full packagetemperature range; 100 nA at 18 V and 25°C
- Noise margin (over full package-temperature range):

$$1 \text{ V at } \text{V}_{\text{DD}} = 5 \text{ V}$$

2.5 V at V_{DD} = 15 V

Meets all requirements of JEDEC Tentative Standard No. 138, "Standard Specifications for Description of 'B' Series CMOS Devices"



Applications:

- Even and odd-parity generators and checkers
- Logical comparators
- Adders/subtractors
- General logic functions

C SUPPLY-VOLTAGE RANGE, (VDD)												
Voltages referenced to VSS Terminal)	•											
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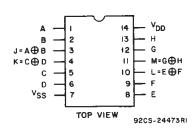
	INPUT VOLTAGE RANGE, ALL INPUTS
	DC INPUT CURRENT, ANY ONE INPUT
	POWER DISSIPATION PER PACKAGE (PD):
	For T _A = -55°C to +100°C
Derate Linearity at 12mW/°C to 200mW	For T _A = +100°C to +125°C
	DEVICE DISSIPATION PER OUTPUT TRANSIS
ANGE (All Package Types) 100mW	FOR TA = FULL PACKAGE-TEMPERATURE
-55°C to +125°C	
-65°C to +150°C	STORAGE TEMPERATURE RANGE (Tsto)
	LEAD TEMPERATURE (DURING SOLDERING

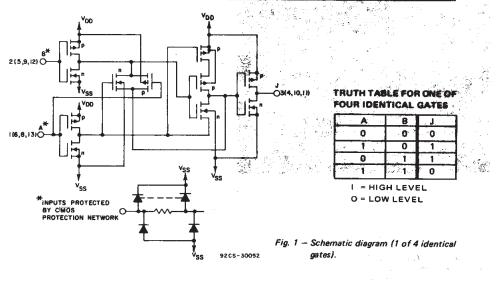
RECOMMENDED OPERATING CONDITIONS

For maximum reliability, nominal operating conditions should be selected so that operation is always within the following ranges:

CHARACTERISTIC	LIM	:	
CHARACTERISTIC	MIN.	MAX.	UNITS
Supply-Voltage Range (For T _A = Full Package) Temperature Range)	3	18	< V







STATIC ELECTRICAL CHARACTERISTICS

CHARAC-	CONE	οιτιο	ONS LIMITS AT INDICATED TEMPERATURES (°C)								U N
TERISTIC	V _O (V)	VIN (V)		55	-40	+85	+125	Min.	+25		Т
	(V)								Тур.	Max.	S
Quiescent		0,5	5	0.25	0.25	7.5	7.5		0.01	0.25	
Device Current, I _{DD}		0,10	10	0.5	0.5	15	15		0.01	0.5	μA
Max.	_	0,15	15	1	1	30	30	·	0.01	1	
	-	0,20	20	5	5	150	150		0.02	5	
Output Low (Sink)	0.4	0,5	5	0.64	0.61	0.42	0.36	0.51	1	-	
Current	0.5	0,10	10	1.6	1.5	1.1	0.9	1.3	2.6	_	
I _{OL} Min.	1.5	0,15	15	4.2	4	2.8	2.4	3.4	6.8	-	
Output High	4.6	0,5	5	-0.64	-0.61	0.42	-0.36	-0.51	-1	-	m
(Source)	2.5	0,5	5	-2	-1.8	-1.3	-1.15	-1.6	-3.2	-	ŀ
Current,	9.5	0,10	10	-1.6	1.5	-1.1	-0.9	-1.3	-2.6		1
IOH Min.	13.5	0,15	15	-4.2	-4	-2.8	-2.4	-3.4	-6.8		1
Output Voltage:		0,5	5		0	.05		_	0	0.05	
Low-Level,	_	0,10	10		0	.05	_		0.05	1	
V _{OL} Max.	-	0,15	15		0	.05	-	0	0.05],	
Output Voltage:	—	0,5	5		4	.95	4.95	5		1	
High-Level,	-	0,10	10		9	.95		9.95	10	-	1
V _{OH} Min.	-	0,15	15		14	.95		14.95	15	-	
Input Low	0.5,4.5	-	5		. 1	.5		_	-	1.5	
Voltage,	1, 9	-	10			3		-		3	
V _{IL} Max.	1.5,13.5	-	15			4		-	-	4	_v
Input High	0.5,4.5	-	5		3	3.5		3.5	-	_	ן י
Voltage,	1,9	-	10			7	Д. – Д	. 7	-	-	
V _{IH} Min.	1.5,13.5	-	15			11		11	-		
Input Current ¹ IN Max.	-	0,18	18	±0.1	±0.1	±1	±1		±10 ⁻⁵	±0.1	μ

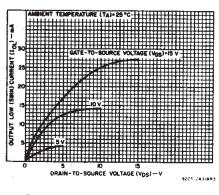


Fig. 2 - Typical output low (sink) current characteristics.

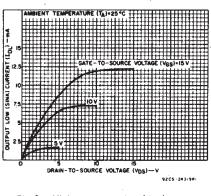
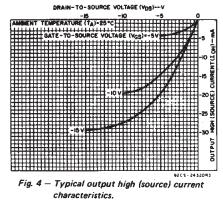
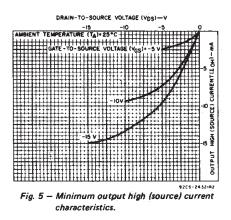


Fig. 3 – Minimum output low (sink) current characteristics.

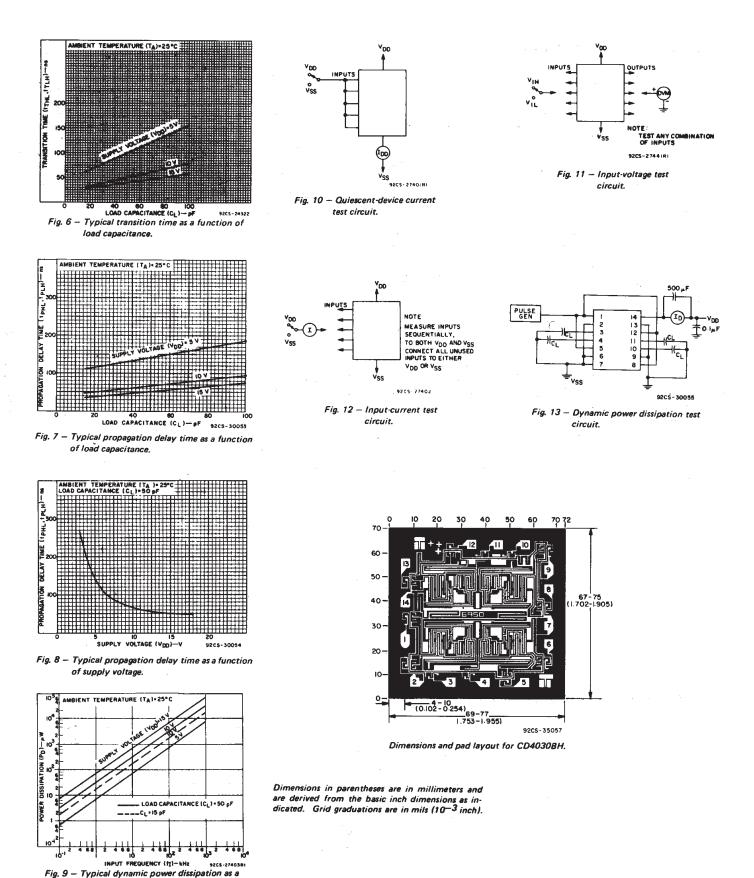


DYNAMIC ELECTRICAL CHARACTERISTICS at $T_A = 25^{\circ}$ C; Input t_r , $t_f = 20$ ns, $C_L = 50$ pF, $R_L = 200$ K Ω

	CONDITIONS				
CHARACTERISTIC	V _{DD}	LIM	LIMITS		
	(V)	Тур.	Max.]	
Propagation Delay Time,		5	140	280	
	^t PLH ^{, t} PHL	10	65	130	ns
		15	50	100	
		5	100	200]
Transition Time,	^t THL ^{, t} TLH	10	50	100	ns
_		15	40	80	1
Input Capacitance,	C _{IN}	Any Input	5	7.5	ρF



3



function of input frequency.



PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
							(6)				
CD4030BE	ACTIVE	PDIP	Ν	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-55 to 125	CD4030BE	Samples
CD4030BEE4	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-55 to 125	CD4030BE	Samples
CD4030BF	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	CD4030BF	Samples
CD4030BF3A	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	CD4030BF3A	Samples
CD4030BM96	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	CD4030BM	Samples
CD4030BM96G4	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	CD4030BM	Samples
CD4030BNSR	ACTIVE	SO	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	CD4030B	Samples
CD4030BNSRG4	ACTIVE	SO	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	CD4030B	Samples
CD4030BPWR	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	CM030B	Samples
JM38510/05353BCA	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 05353BCA	Samples
M38510/05353BCA	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 05353BCA	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.



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PACKAGE OPTION ADDENDUM

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF CD4030B, CD4030B-MIL :

Catalog : CD4030B

• Military : CD4030B-MIL

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications



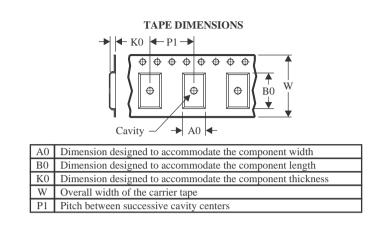
Texas

*All dimensions are nominal

STRUMENTS

TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD4030BM96	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
CD4030BM96G4	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
CD4030BNSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
CD4030BPWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1



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PACKAGE MATERIALS INFORMATION

16-Apr-2024



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CD4030BM96	SOIC	D	14	2500	356.0	356.0	35.0
CD4030BM96G4	SOIC	D	14	2500	356.0	356.0	35.0
CD4030BNSR	SO	NS	14	2000	356.0	356.0	35.0
CD4030BPWR	TSSOP	PW	14	2000	356.0	356.0	35.0

TEXAS INSTRUMENTS

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16-Apr-2024

TUBE



- B - Alignment groove width

*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
CD4030BE	N	PDIP	14	25	506	13.97	11230	4.32
CD4030BE	N	PDIP	14	25	506	13.97	11230	4.32
CD4030BEE4	N	PDIP	14	25	506	13.97	11230	4.32
CD4030BEE4	N	PDIP	14	25	506	13.97	11230	4.32

MECHANICAL DATA

PLASTIC SMALL-OUTLINE PACKAGE

0,51 0,35 ⊕0,25⊛ 1,27 8 14 0,15 NOM 5,60 8,20 5,00 7,40 \bigcirc Gage Plane ₽ 0,25 7 1 1,05 0,55 0-10 Δ 0,15 0,05 Seating Plane — 2,00 MAX 0,10PINS ** 14 16 20 24 DIM 10,50 10,50 12,90 15,30 A MAX A MIN 9,90 9,90 12,30 14,70 4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.

NS (R-PDSO-G**)

14-PINS SHOWN

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



GENERIC PACKAGE VIEW

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



Images above are just a representation of the package family, actual package may vary. Refer to the product data sheet for package details.



J0014A



PACKAGE OUTLINE

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



NOTES:

- 1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. This package is hermitically sealed with a ceramic lid using glass frit.
- Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
 Falls within MIL-STD-1835 and GDIP1-T14.



J0014A

EXAMPLE BOARD LAYOUT

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE





D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.





NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



A. An integration of the information o

Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.

Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.

E. Falls within JEDEC MO-153



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- \triangle The 20 pin end lead shoulder width is a vendor option, either half or full width.



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